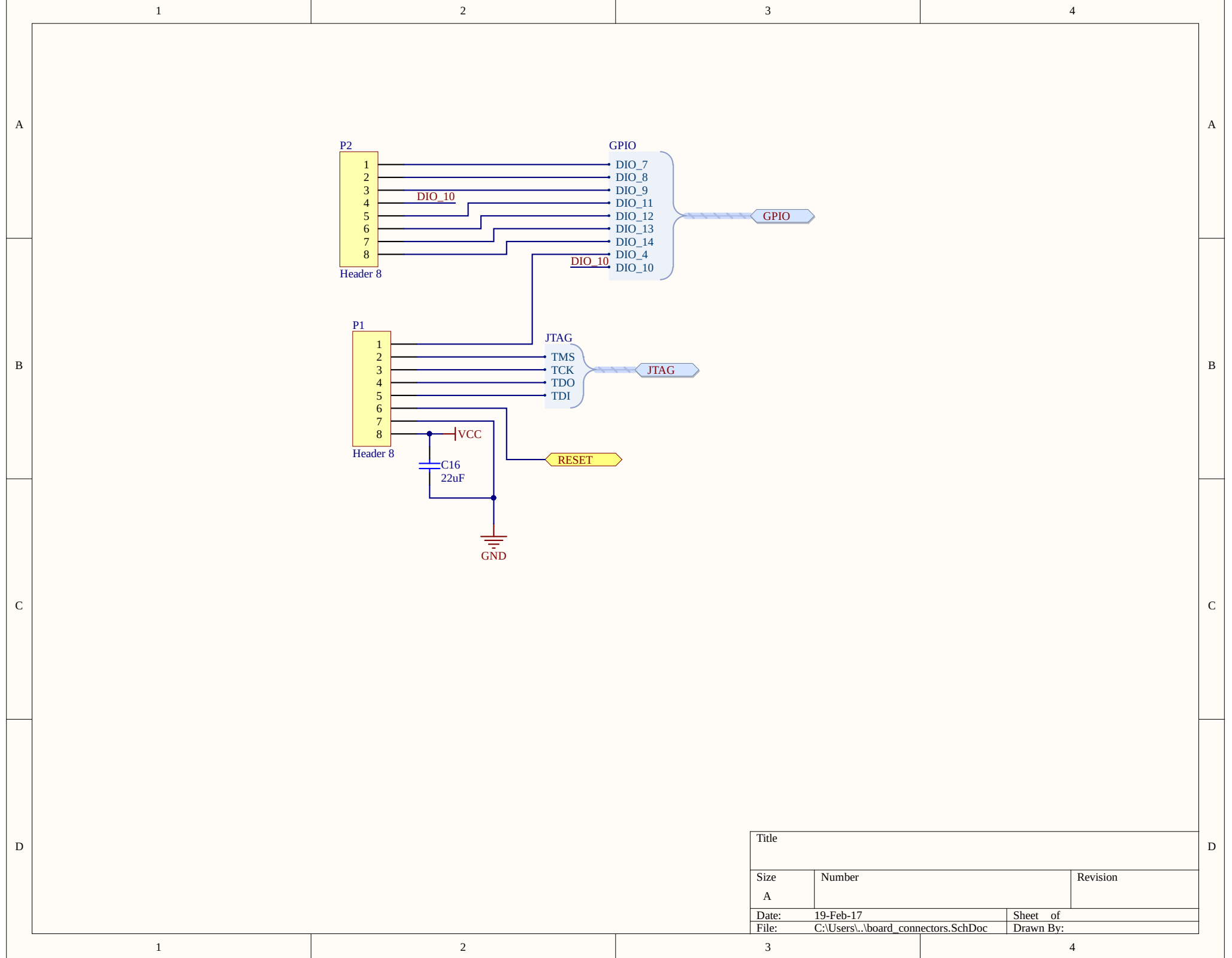
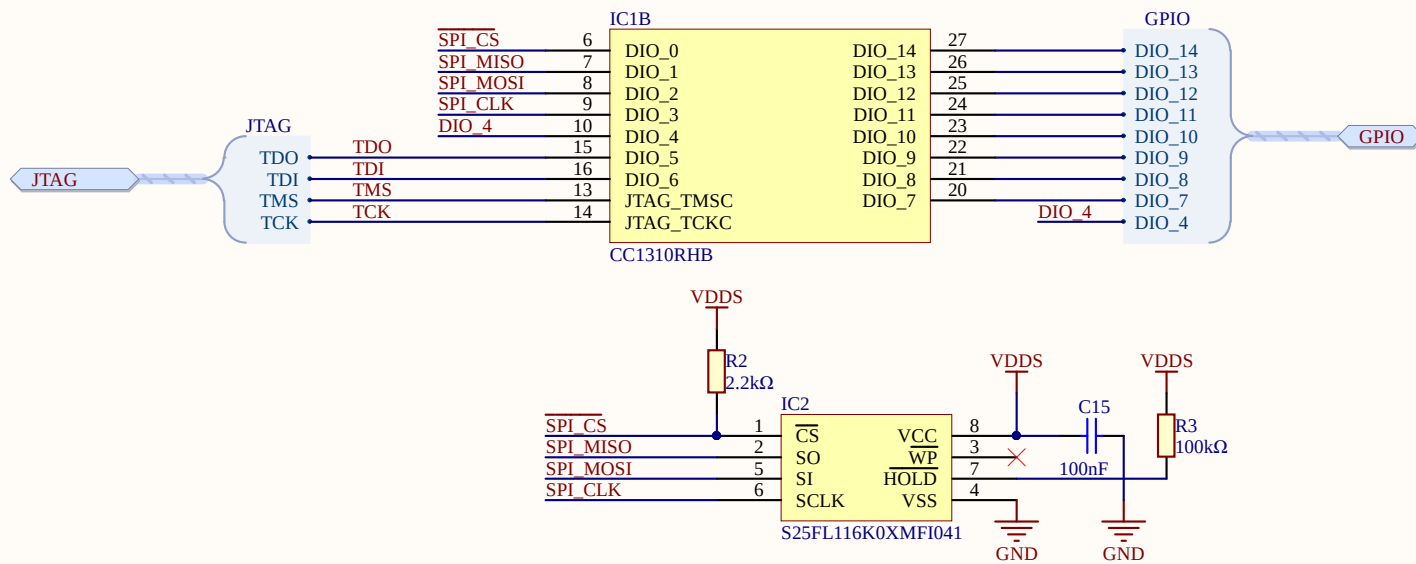
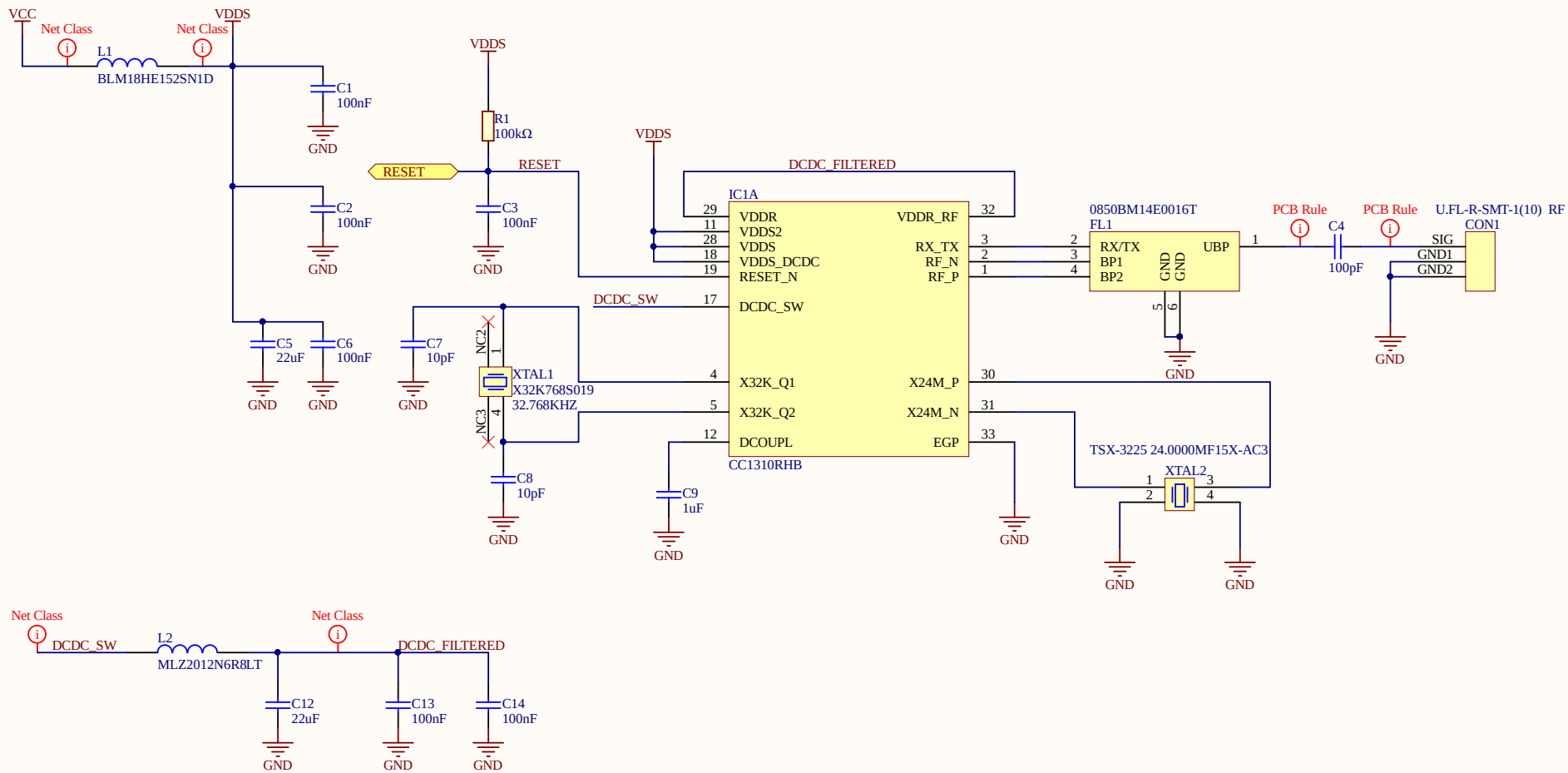






Title			
Size	Number		Revision
A			
Date:	19-Feb-17		Sheet of
File:	C:\Users\...\mcu_gpio.SchDoc		Drawn By:



Title		
Size	Number	Revision
A4		
Date:	19-Feb-17	Sheet of
File:	C:\Users\...\mcu_supply\SchDoc	Drawn By:

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.38mil		
4	Dielectric 1	FR-4	6.89mil	4.29	
5	Ground Plane	Copper	1.38mil		
6	Dielectric 3		44.49mil	3.96	
7	Power Plane	Copper	1.38mil		
8	Dielectric 4		6.89mil	4.2	
9	Bottom Layer	Copper	1.38mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

